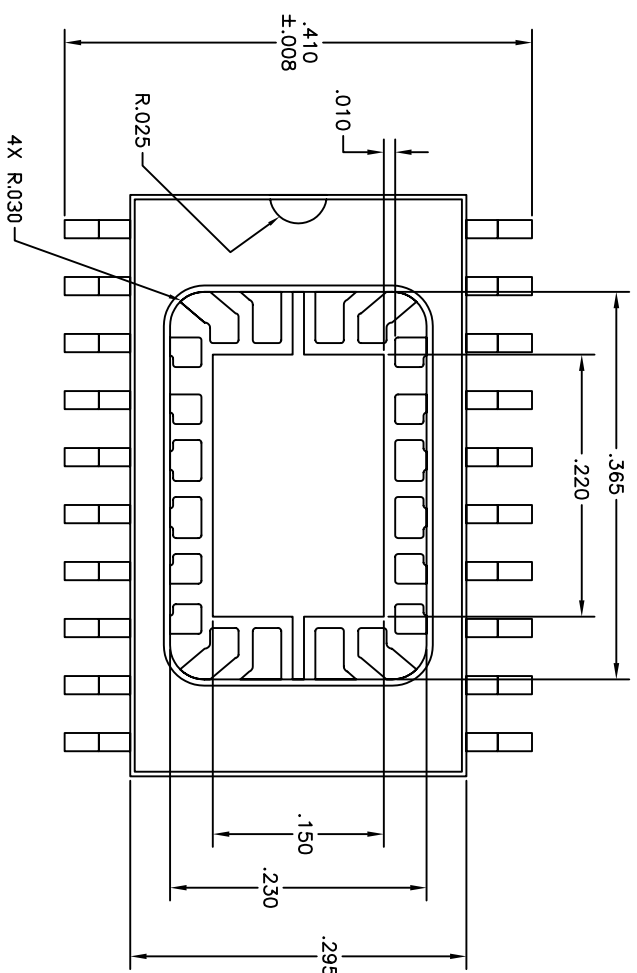
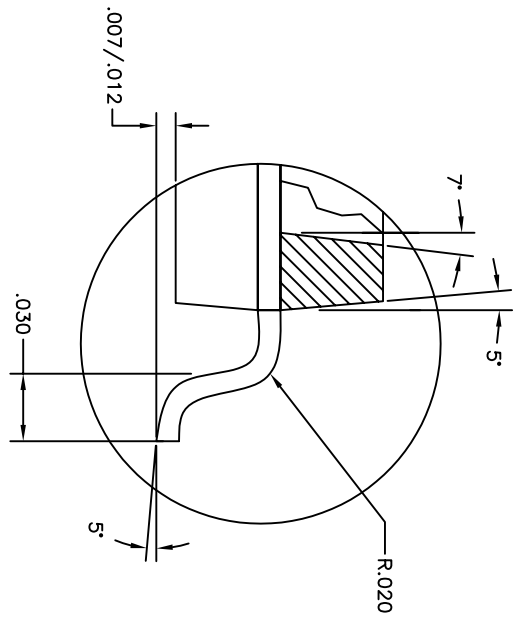


2

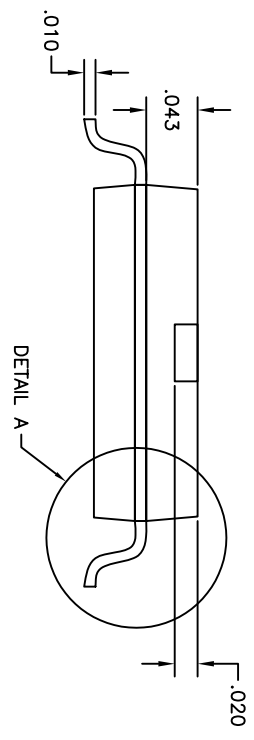
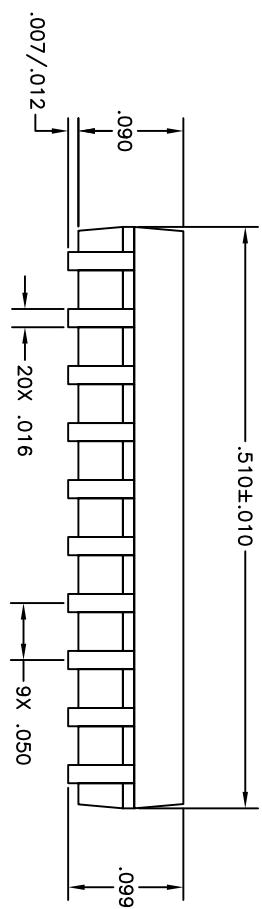


1

REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	D.BENAVANDO
10513	11/2/05	PRODUCTION RELEASE	



DETAIL A  
SCALE: 2/1



NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEADFRAME: COPPER, FH 194.
3. LEAD FINISH: FULL Au PLATE.
4. DIE PAD: .220" x .150".



THIRD ANGLE  
PROJECTION

UNLESS OTHERWISE SPECIFIED  
DIMENSIONS ARE IN INCHES  
TOLERANCES ARE:  
XXX ± 0.01    X.XXXX ± ---  
XXXX ± 0.005    ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN BY W. GRIFFITTS	DATE 11/1/05
APP BY P. FLASKERUD	DATE 11/1/05
CUSTOMER ---	

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SIZE A	PART NO. SOIC300-20-0P-01	REV 3
SCALE NONE	FILE SOIC300-20-0P-01-R3.DWG	SHEET 1 OF 1

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